

EP1100HSTSL-2.4576M

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REGULATORY COMPLIANCE (Data Sheet downloaded on Apr 1, 2017)


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ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) HCMOS/TTL (CMOS) 5.0Vdc 8 Pin DIP Metal Thru-Hole 2.4576MHz ±100ppm -20°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	2.4576MHz
Frequency Tolerance/Stability	±100ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Aging at 25°C	±5ppm/year Maximum
Operating Temperature Range	-20°C to +70°C
Supply Voltage	5.0Vdc ±10%
Input Current	45mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	2.4Vdc Minimum (IOH=-16mA)
Output Voltage Logic Low (Vol)	0.4Vdc Maximum (IOL=+16mA)
Rise/Fall Time	4nSec Maximum (Measured at 0.8Vdc to 2.0Vdc)
Duty Cycle	50 ±10(%) (Measured at 1.4Vdc with TTL Load; Measured at 50% of waveform with HCMOS Load)
Load Drive Capability	10TTL Load Maximum
Output Logic Type	TTL
Pin 1 Connection	Tri-State (Disabled Output: High Impedance)
Pin 1 Input Voltage (Vih and Vil)	+2.0Vdc Minimum to enable output, +0.8Vdc Maximum to disable output, No Connect to enable output.
Disable Current	30mA Maximum (Pin 1 = Ground)
Standby Current	50µA Maximum (Pin 1 = Ground)
Peak to Peak Jitter (tPK)	500pSec Maximum, 90pSec Typical
RMS Period Jitter (tRMS)	50pSec Maximum, 13pSec Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

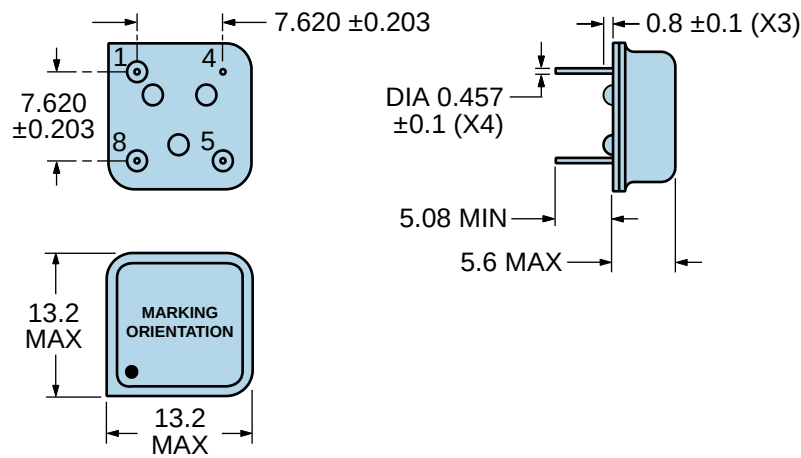
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



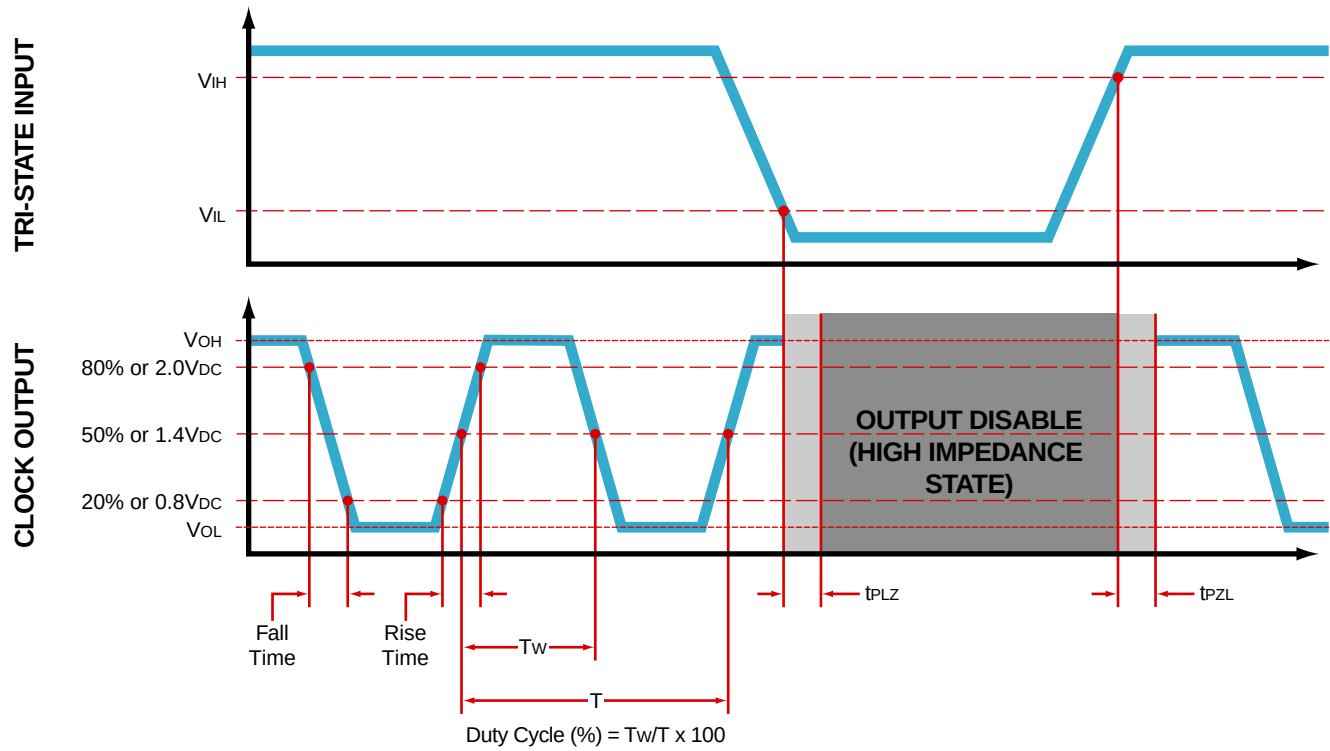
PIN	CONNECTION
1	Tri-State (High Impedance)
4	Case/Ground
5	Output
8	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	EP11TS EP11=Product Series
3	2.4576M
4	XXYZZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

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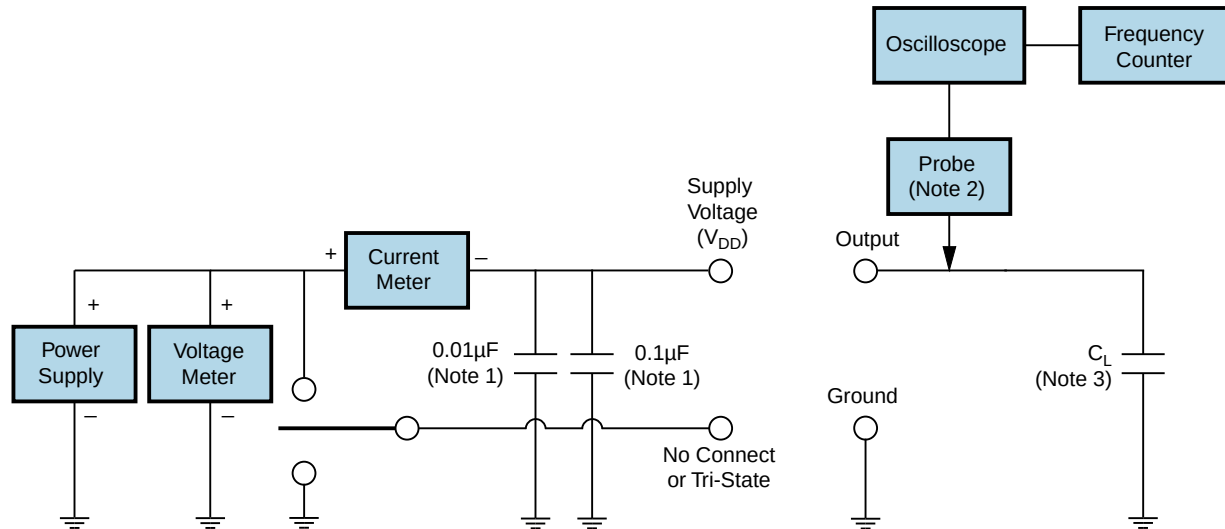
OUTPUT WAVEFORM & TIMING DIAGRAM



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Test Circuit for CMOS Output



Note 1: An external 0.1 μF low frequency tantalum bypass capacitor in parallel with a 0.01 μF high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

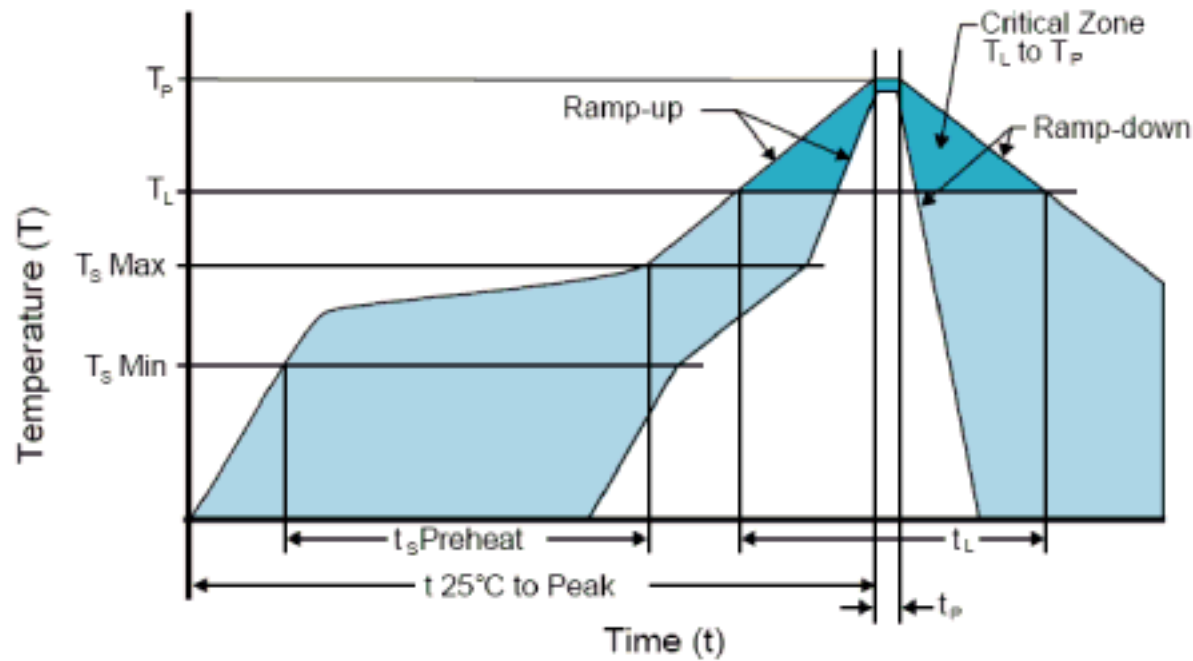
Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

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Recommended Solder Reflow Methods



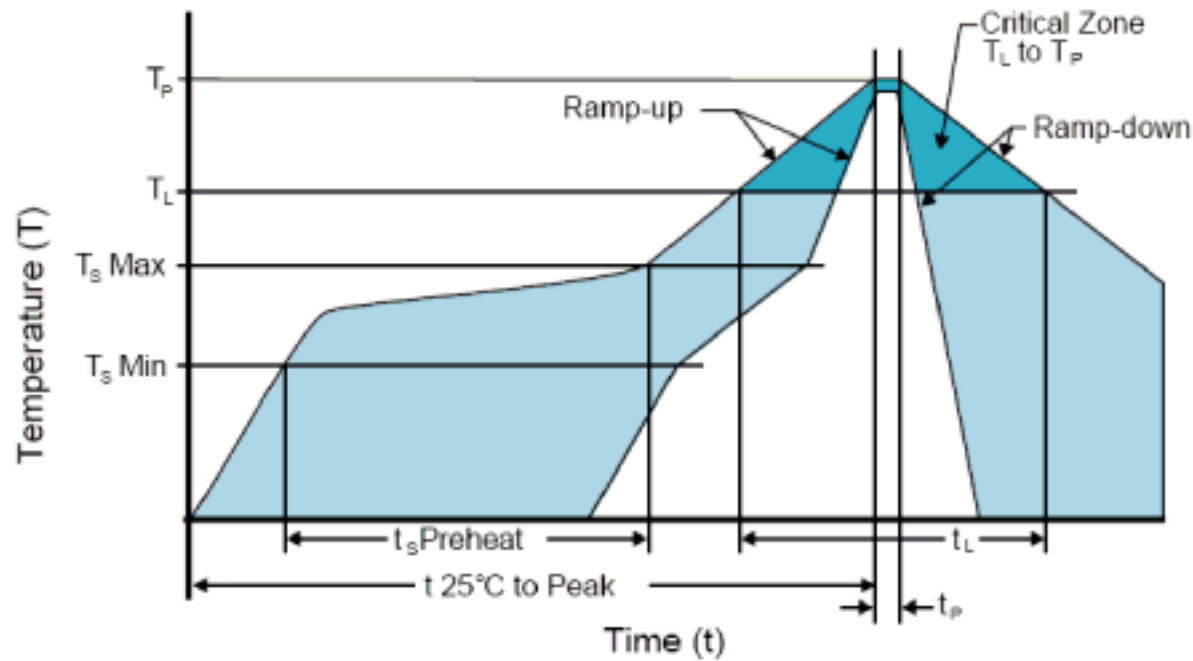
High Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)		3°C/Second Maximum
Preheat		
- Temperature Minimum (TS MIN)	150°C	
- Temperature Typical (TS TYP)	175°C	
- Temperature Maximum (TS MAX)	200°C	
- Time (ts MIN)	60 - 180 Seconds	
Ramp-up Rate (TL to TP)		3°C/Second Maximum
Time Maintained Above:		
- Temperature (TL)	217°C	
- Time (tL)	60 - 150 Seconds	
Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature (TP Target)	250°C +0/-5°C	
Time within 5°C of actual peak (tp)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	

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Recommended Solder Reflow Methods



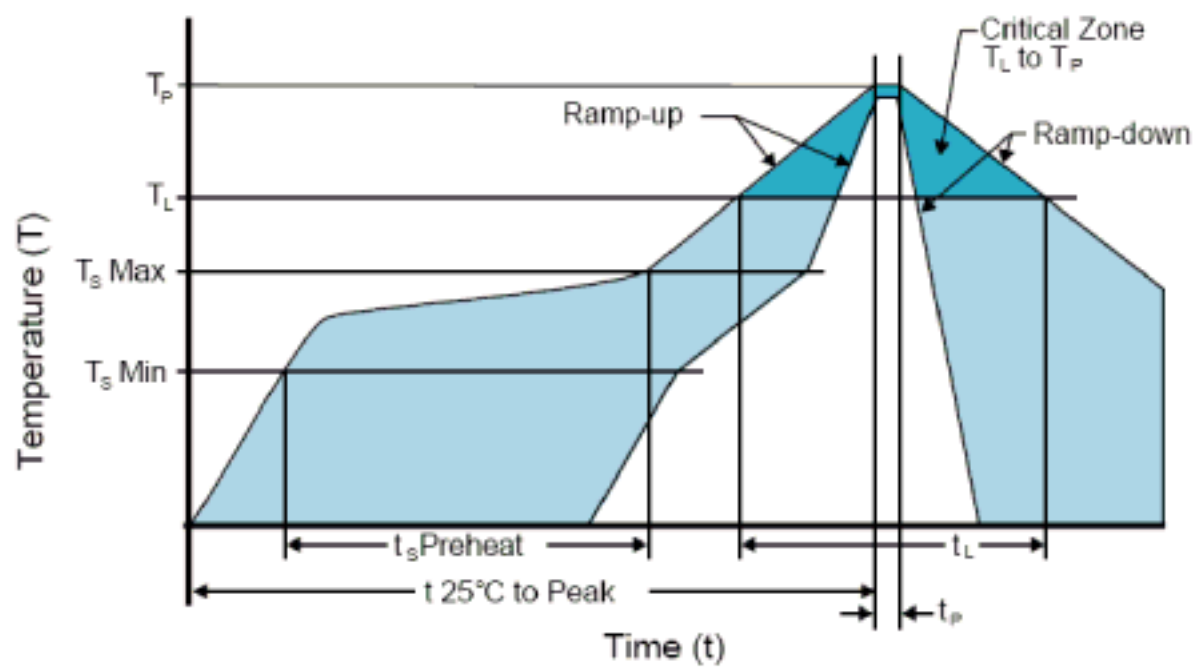
Low Temperature Infrared/Convection 185°C

TS MAX to TL (Ramp-up Rate)		5°C/Second Maximum
Preheat		
- Temperature Minimum (TS MIN)	N/A	
- Temperature Typical (TS TYP)	150°C	
- Temperature Maximum (TS MAX)	N/A	
- Time (ts MIN)	60 - 120 Seconds	
Ramp-up Rate (TL to TP)		5°C/Second Maximum
Time Maintained Above:		
- Temperature (TL)	150°C	
- Time (tL)	200 Seconds Maximum	
Peak Temperature (TP)		185°C Maximum
Target Peak Temperature (TP Target)		185°C Maximum 2 Times
Time within 5°C of actual peak (tp)		10 Seconds Maximum 2 Times
Ramp-down Rate		5°C/Second Maximum
Time 25°C to Peak Temperature (t)		N/A
Moisture Sensitivity Level		Level 1

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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	245°C Maximum
Target Peak Temperature (TP Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (tp)	5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.